

MNDS26F32M-X-RH REV 0C0

Original Creation Date: 05/20/99

Last Update Date: 05/04/01

Last Major Revision Date:

**QUAD DIFFERENTIAL LINE RECEIVERS ALSO AVAILABLE
 GUARANTEED TO 100K RAD(Si) TESTED TO MIL-STD-883,
 METHOD 1019.5, CONDITION A**

General Description

The DS26F32 is a quad differential line receiver designed to meet the requirements of EIA Standards RS-422 and RS-423, and Federal Standards 1020 and 1030 for balanced and unbalanced digital data transmission.

The DS26F32 offers improved performance due to the use of state-of-the-art L-FAST bipolar technology. The L-FAST technology allows for higher speeds and lower currents by utilizing extremely short gate delay times.

The device features an input sensitivity of 200mV over the input common mode range of $\pm 7.0V$. The DS26F32 provides an enable function common to all four receivers and TRI-STATE outputs with 8.0 mA sink capability. Also, a fail-safe input/output relationship keeps the outputs high when the inputs are open.

The DS26F32 offers optimum performance when used with the DS26F31 Quad Differential Line Driver.

Industry Part Number

DS26F32

Prime Die

M632

Controlling Document

SEE FEATURES SECTION

NS Part Numbers

 DS26F32ME/883
 DS26F32MER-QML
 DS26F32MJ-QMLV
 DS26F32MJ/883
 DS26F32MJR-QML
 DS26F32MJRQMLV
 DS26F32MW-QMLV
 DS26F32MW/883
 DS26F32MWG/883
 DS26F32MWGRQMLV
 DS26F32MWR-QML
 DS26F32MWRQMLV

Processing

MIL-STD-883, Method 5004

Quality Conformance Inspection

MIL-STD-883, Method 5005

Subgrp Description
Temp (°C)

1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

Features

- Military temperature range
- Input voltage range of $\pm 7.0V$ (differential or common mode) $\pm 0.2V$ sensitivity over the input voltage range.
- High input impedance
- Operation from single +5.0V supply
- Input pull-down resistor prevents output oscillation on unused channels
- TRI-STATE outputs, with choice of complementary enables, for receiving directly on a data bus

CONTROLLING DOCUMENTS:

DS26F32ME/883	5962-7802005M2A
DS26F32MER-QML	5962R7802005Q2A
DS26F32MJ-QMLV	5962-7802005VEA
DS26F32MJ/883	5962-7802005MEA
DS26F32MJR-QML	5962R7802005QEA
DS26F32MJRQMLV	5962R7802005VEA
DS26F32MW-QMLV	5962-7802005VFA
DS26F32MW/883	5962-7802005MFA
DS26F32MWG/883	5962-7802005MZA
DS26F32MWGRQMLV	5962R7802005VZA
DS26F32MWR-QML	5962R7802005QFA
DS26F32MWRQMLV	5962R7802005VFA

(Absolute Maximum Ratings)

(Note 1)

Storage Temperature Range	-65 C ≤ Ta ≤ +150 C
Operating Temperature Range	-55 C ≤ Ta ≤ +125 C
Lead Temperature Soldering, 60 seconds	300 C
Supply Voltage	7.0V
Common Mode Voltage Range	±25V
Differential Input Voltage	±25V
Enable Voltage	7.0V
Output Sink Current	50mA
Maximum Power Dissipation (Pd) @ +25C (Note 2)	500mW
Thermal Resistance (JA)	
J package	100 C/W
W package	142 C/W
E package	87 C/W

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.

Note 2: Derate J package 10.0mW/C above +25C, Derate W package 7.1mW/C above +25C, Derate E package 11.5mW/C above +25C

Recommended Operating Conditions

Operating Temperature	-55 C ≤ Ta ≤ +125 C
Supply Voltage	4.5V to 5.5V

Electrical Characteristics

DC PARAMETERS: (SEE Note 5)

(The following conditions apply to all the following parameters, unless otherwise specified.)
DC: $V_{CC} = 5V$

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
I _{in}	Input Current	$V_{CC}=4.5V$, $V_{in}=15V$ (Pin under test), other inputs $-15V \leq V_{in} \leq +15V$				2.3	mA	1, 2, 3
		$V_{CC}=5.5V$, $V_{in}=-15V$ (Pin under test), other inputs $-15V \leq V_{in} \leq +15V$				-2.8	mA	1, 2, 3
I _{il}	Logical "0" Enable Current	$V_{CC} = 5.5V$, $V_{en} = .4V$				-360	uA	1, 2, 3
I _{ih}	Logical "1" Enable Current	$V_{CC} = 5.5V$, $V_{in} = 2.7V$				10	uA	1, 2, 3
I _i	Logical "1" Enable Current	$V_{CC} = 5.5V$, $V_{in} = 5.5V$				50	uA	1, 2, 3
V _{ik}	Input Clamp Voltage (Enable)	$V_{CC} = 4.5V$, $I_{in} = -18mA$				-1.5	V	1, 2, 3
V _{oh}	Logical "1" Output Voltage	$V_{CC} = 4.5V$, $I_{oh} = -440uA$, $\Delta V_{in} = 1V$, $\overline{V_{en}} = .8 = V_{en}$			2.5		V	1, 2, 3
V _{ol}	Logical "0" Output Voltage	$V_{CC} = 4.5V$, $\overline{V_{en}} = .8V = V_{en}$, $I_{ol} = 4mA$, $\Delta V_{in} = -1V$.4	V	1, 2, 3
		$V_{CC} = 4.5V$, $\overline{V_{en}} = .8V = V_{en}$, $I_{ol} = 8mA$, $\Delta V_{in} = -1V$.45	V	1, 2, 3
I _{cc}	Supply Current	$\overline{V_{CC}} = 5.5V$, All $V_{in} = Gnd$, $V_{en} = 0V$, $\overline{V_{en}} = 2V$				50	mA	1, 2, 3
I _{oz}	Off-State Output Current	$\overline{V_{CC}} = 5.5V$, $V_o = .4V$, $V_{en} = .8V$, $\overline{V_{en}} = 2V$				-20	uA	1, 2, 3
		$\overline{V_{CC}} = 5.5V$, $V_o = 2.4V$, $V_{en} = .8V$, $\overline{V_{en}} = 2V$				20	uA	1, 2, 3
R _{in}	Input Resistance	$-15 \leq V_{cm} \leq 15V$			14		KOhm	1, 2, 3
V _{th}	Differential Input Voltage	$V_{CC} = 4.5V$, $-7V \leq V_{cm} \leq 7V$, $V_{en} = \overline{V_{en}} = 2.5V$, $V_o = 0.45/2.5V$	2		-0.2	0.2	V	1, 2, 3
		$V_{CC} = 5.5V$, $-7V \leq V_{cm} \leq 7V$, $V_{en} = \overline{V_{en}} = 2.5V$, $V_o = 0.45/2.5V$	2		-0.2	0.2	V	1, 2, 3
V _{il}	Logical "0" Input Voltage (Enable)	$V_{CC} = 5.5V$	2			.8	V	1, 2, 3
V _{ih}	Logical "1" Input Voltage (Enable)	$V_{CC} = 4.5V$	2		2		V	1, 2, 3
I _{sc (min)}	Output Short Circuit Current	$V_{CC} = 4.5V$, $V_o = 0V$, $\Delta V_{in} = 1V$			-15		mA	1, 2, 3
I _{sc (max)}	Output Short Circuit Current	$V_{CC} = 5.5V$, $V_o = 0V$, $\Delta V_{in} = 1V$				-85	mA	1, 2, 3

Electrical Characteristics

AC PARAMETERS: PROPAGATION DELAY TIME: (SEE NOTE 5)

(The following conditions apply to all the following parameters, unless otherwise specified.)
AC: $V_{cc} = 5V$

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
tPLH		Cl = 50pF	4, 5			23	nS	9
			4, 5			31	nS	10, 11
		Cl = 15pF	3, 5			22	nS	9
			3, 5			30	nS	10, 11
tPHL		Cl = 50pF	4, 5			23	nS	9
			4, 5			31	nS	10, 11
		Cl = 15pF	3, 5			22	nS	9
			3, 5			30	nS	10, 11
tPZH	Enable Time	Cl = 50pF	4, 5			18	nS	9
			4, 5			29	nS	10, 11
		Cl = 15pF	3, 5			16	nS	9
			3, 5			27	nS	10, 11
tPZL	Enable Time	Cl = 50pF	4, 5			20	nS	9
			4, 5			29	nS	10, 11
		Cl = 15pF	3, 5			18	nS	9
			3, 5			27	nS	10, 11
tPHZ	Disable Time	Cl = 50pF	4, 5			55	nS	9
			4, 5			62	nS	10, 11
		Cl = 5pF	3, 5			20	nS	9
			3, 5			27	nS	10, 11
tPLZ	Disable Time	Cl = 50pF	4, 5			30	nS	9
			4, 5			42	nS	10, 11
		Cl = 5pF	3, 5			18	nS	9
			3, 5			30	nS	10, 11

Electrical Characteristics

DC PARAMETERS - DRIFT VALUES

(The following conditions apply to all the following parameters, unless otherwise specified.)
 DC: NOTE::This section applies to -QMLV devices only and shall be read & recorded at TA = +25C before and after each burn-in and shall not change by more than the limits indicated. The delta rejects shall be included in the PDA calculation.

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
Voh	Logical "1" Output Voltage	Vcc = 4.5V, Ioh = -440uA, Delta Vin = 1V, Ven = 0.8V = Ven			-250	250	mV	1
Vol	Logical "0" Output Voltage	Vcc = 4.5V, Iol = 4mA, Delta Vin = -1V, Ven = 0.8V = Ven			-45	45	mV	1
		Vcc = 4.5V, Iol = 8mA, Delta Vin = -1V, Ven = 0.8V = Ven			-45	45	mV	1
Iin	Input Current	Vcc = 4.5V, Vin=15V (Pin under test), other inputs -15V <= Vin <= +15V			-0.28	0.28	mA	1
		Vcc = 5.5V, Vin=-15V (Pin under test), other inputs -15V <= Vin <= +15V			-0.28	0.28	mA	1

Note 1: Power dissipation must be externally controlled at elevated temperatures.

Note 2: Parameter tested go-no-go only.

Note 3: Tested at 50pF guarantees limit at 15 & 5pF.

Note 4: Tested at 50pF, system capacitance exceeds 5 to 15pF.

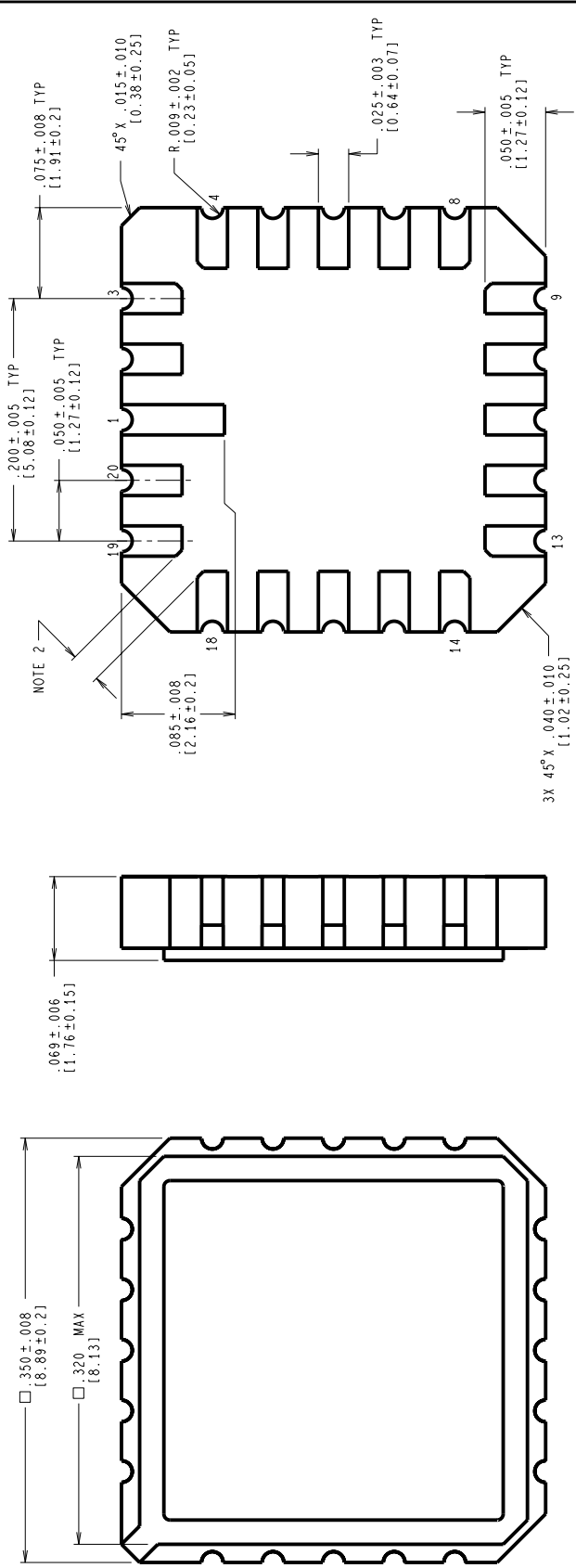
Note 5: Pre and post irradiation limits are identical to those listed under AC and DC electrical characteristics. These parts may be dose rate sensitive in a space environment and demonstrate enhanced low dose rate effect. Radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, Method 1019.5, Condition A.

Graphics and Diagrams

GRAPHICS#	DESCRIPTION
E20ARE	LCC (E), TYPE C, 20 TERMINAL(P/P DWG)
J16ARL	CERDIP (J), 16 LEAD (P/P DWG)
W16ARL	CERPACK (W), 16 LEAD (P/P DWG)
WG16ARC	CERAMIC SOIC (WG), 16 LEAD (P/P DWG)

See attached graphics following this page.

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
E	REVISE AND REDRAW	10005	02/10/94 DEG/

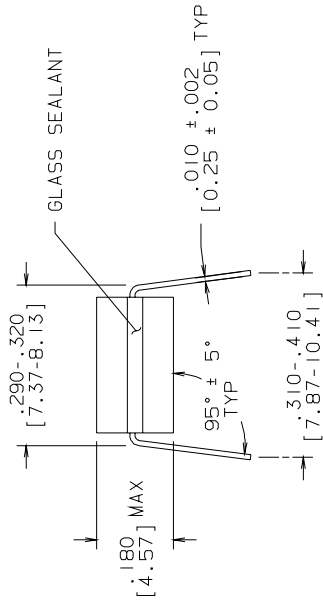
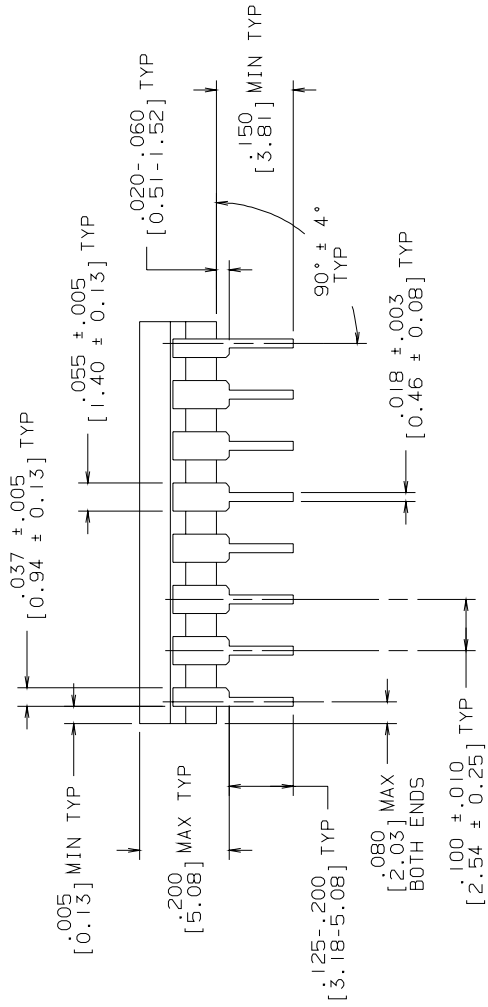
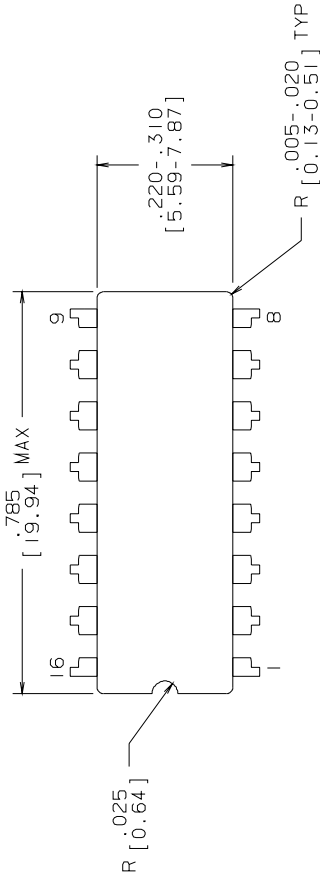


- NOTES: UNLESS OTHERWISE SPECIFIED.
- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 50 MICRONS/12.7 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICRONS/1.27-8.89 MICROMETERS NICKEL.
 - SOLDER DIP. SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.
 - CORNER PADS MAY HAVE A $45^\circ \times .020 \text{ IN}/0.51 \text{ mm}$ MAXIMUM CHAMFER TO ACCOMPLISH THE $.015 \text{ IN}/0.38 \text{ mm}$ DIMENSION.
 - REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL/AERO CONFIGURATION CONTROL		NATIONAL SEMICONDUCTOR CORPORATION <small>2300 Semiconductor Drive, Santa Clara, Ca. 95052-8090</small>	
		LEADLESS CHIP CARRIER, TYPE C, 20 TERMINAL	
APPROVALS <small>DRN: Deane Gedy</small> <small>DWG. CHK.</small> <small>ENGR. CHK.</small> <small>APPROVAL</small>	DATE 02/10/94	SCALE N/A	SIZE C
	DRAWING NUMBER MKT-E20A	REV E	SHEET 1 of 1

R E V I S I O N S			
LTR	DESCRIPTION	E. C. N.	DATE
L	REVISE PER CURRENT STD; REDRAW	09996	09/15/93
			TL/



MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

CONTROLLING DIMENSION: INCH	
APPROVALS	DATE
DRAWN T. LEQUANG	09/15/93
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	
PROJECTION 	
SCALE N/A	SIZE B
DRAWING NUMBER MKT-J16A	REV L
DO NOT SCALE DRAWING	SHEET 1 OF 1

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

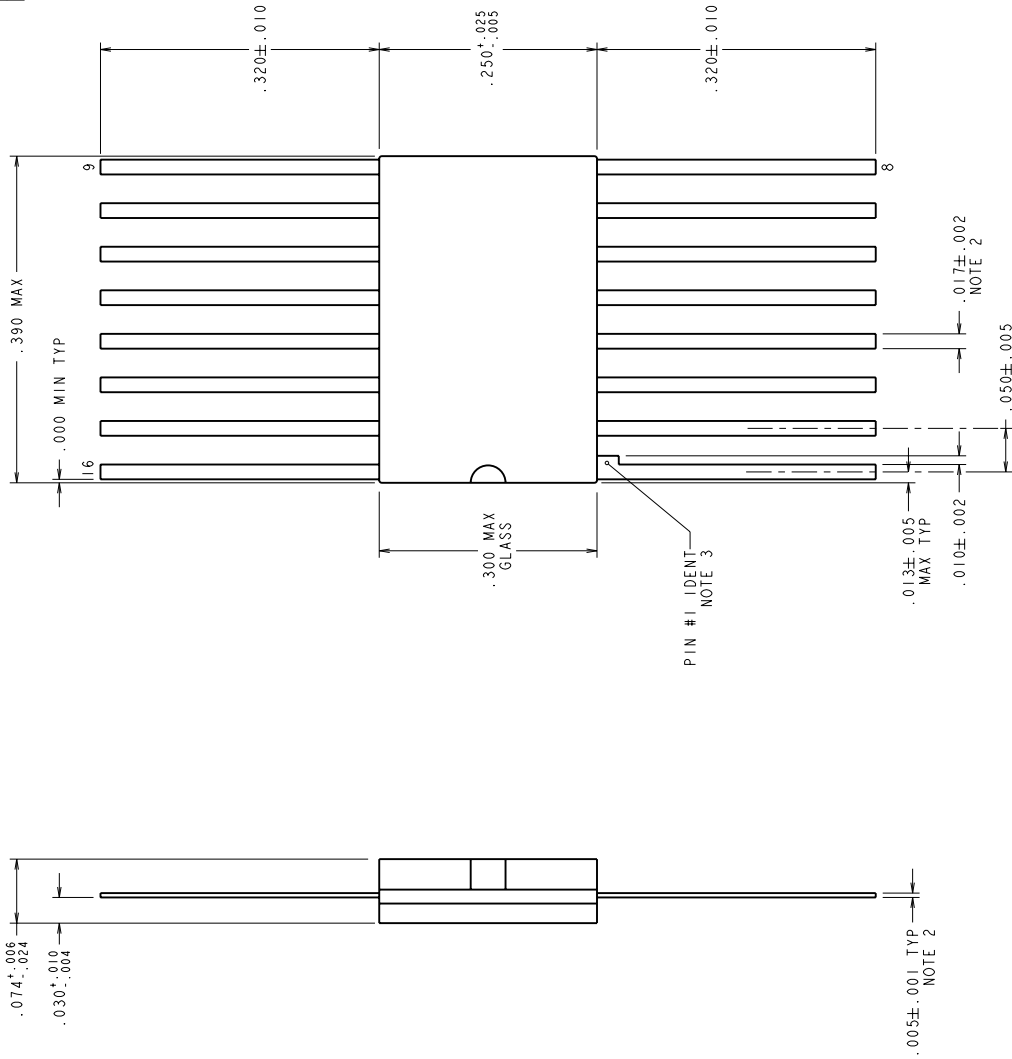
CERDIP (J),
16 LEAD

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE 200 MICROMETERS / 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- JEDEC REGISTRATION MO-036, VARIATION AD, DATED 04/1981.

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE AND REDRAW PER NEW STANDARD.	10514	07/28/94	DEG/AEP
L	.017±.002 WAS .017±.020.	10656	10/21/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-M-38510 TO A MINIMUM THICKNESS OF 200 MICROINCHES. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
 - a) A NOTCH OR OTHER MARK WITHIN THIS AREA
 - b) A TAB ON LEAD 1, EITHER SIDE
4. REFERENCE JEDEC REGISTRATION M0-092, VARIATION AC, DATED 04/89.

MIL/AERO
CONFIGURATION CONTROL


MIL-M-38510
CONFIGURATION CONTROL

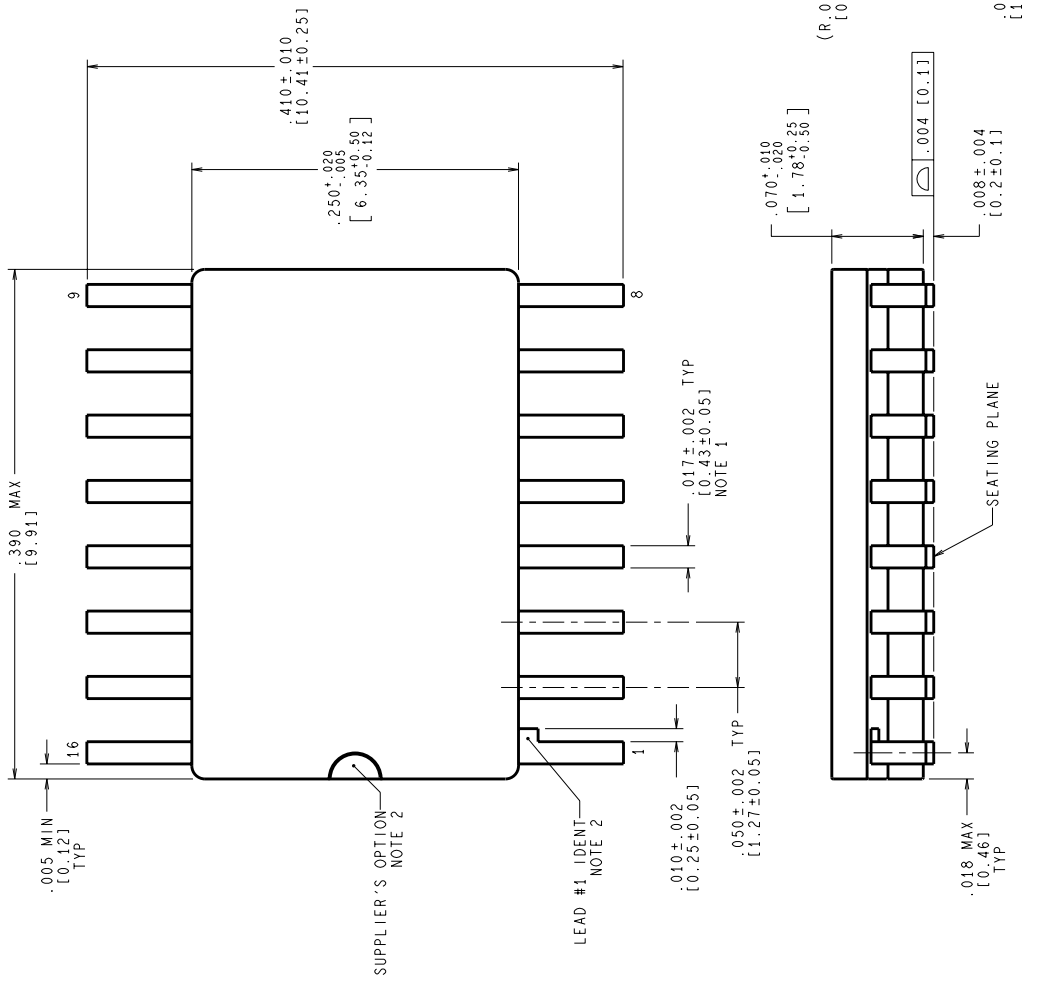
APPROVALS	DATE
DRWN: <i>D.F. Grady</i>	07/28/94
DTG. CHK.	
ENGR. CHK.	

PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-W16A	L
DO NOT SCALE DRAWING SHEET 1 of 1					

		National Semiconductor	
2800 Semiconductor dr., Santa Clara, CA 95052-8090			
CERPACK, 16 LEAD			

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
A	RELEASE TO DOCUMENT CONTROL	11376	02/29/1996
B	LD PITCH TOL WAS ±.005; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R.006±.002; DIM. .040±.003 WAS .037±.003	11443	04/19/1996
C	R.015(0.38) WAS R.006(0.15)	11840	10/08/1997

APPROVALS	DATE	BY/APP'D
DRN: <i>MARYA SUCHY</i>	02/29/96	MS/KH
ENGR. CHK.		MS/KH
PROJECTION		
		
SCALE	SIZE	REV
N/A	C	C
DO NOT SCALE DRAWING		



**MIL-PRF-38535
CONFIGURATION CONTROL**

CONTROLLING DIMENSION IS INCH
VALUES IN | ARE MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICRONS / 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN / 0.08mm AFTER LEAD FINISH APPLIED.
 - LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
 - NO JEDEC REGISTRATION AS OF FEBRUARY 1996.

National Semiconductor
2800 Semiconductor Dr., Santa Clara, CA 95052-8000

**CERPACK,
16 LEAD,
GULL WING**

SCALE: N/A C (SC) MKT-WG16A REV: C

DO NOT SCALE DRAWING SHEET 1 of 1

Revision History

Rev	ECN #	Rel Date	Originator	Changes
0A0	M0003443	08/22/00	Rose Malone	Initial MDS Release: MNDS26F32M-X-RH, Rev. 0A0 - Added reference to Rad Hard. Archive MNDS26F32M-X, Rev. 0B0, Replace By MNDS26F32M-X-RH, Rev. 0A0.
0B0	M0003730	05/04/01	Rose Malone	Update MDS: MNDS26F32M-X-RH, Rev. 0A0 to MNDS26F32M-X-RH, Rev. 0B0. Changed Main Table and Features Section reference to Rad Hard NS Part Numbers and 5962 SMD Drawings for J, E and W Packages. Rad Hard Level from 300K to 100K.
0C0	M0003796	05/04/01	Rose Malone	Update MDS: MNDS26F32M-X-RH, Rev. 0B0 to MNDS26F32M-X-RH, Rev. 0C0. Added to Main Table NS Part Numbers Section and Features Section reference to WG package and SMD numbers and Marketing Dwg. to Graphics Section.